Semiconductor Device Type:	E5X	TQFP-100-14x14x1mm-MatteTin			
Basic Substance	**CAS Number**	**"Contained In" Sub-Component**	**% Total Weight**	**mg/part**	**ppm**
Solid Epoxy Resin-1	Trade Secret	Mold compound	2.58	13.54	25771
Solid Epoxy Resin-2	Trade Secret	Mold compound	3.72	19.55	37225
Hardener	Trade Secret	Mold compound	3.44	18.05	34362
Carbon Black	1333-86-4	Mold compound	0.29	1.50	2863
Amorphous Silica	60676-86-0	Mold compound	47.25	248.15	472477
Copper	7440-50-8	Leadframe	36.48	191.61	364826
Magnesium	7439-95-4	Leadframe	0.06	0.33	635
Nickel	7440-02-0	Leadframe	1.16	6.09	11590
Silicon	7440-21-3	Leadframe	0.26	1.37	2618
Silver	7440-22-4	Leadframe	2.00	10.50	19983
Silicon	7440-21-3	Die	1.03	5.43	10331
Silver Flake	7440-22-4	Epoxy	0.11	0.57	1092
Epoxy Acylate	15625-89-5	Epoxy	0.01	0.06	108
Substituted Polyamine	68490-66-4	Epoxy	0.00	0.02	29
Bisphenol F	28064-14-4	Epoxy	0.01	0.08	145
2-Ethylhexyl Glycidyl Ether	2461-15-6	Epoxy	0.01	0.04	72
Copper	7440-50-8	Wire	0.15	0.76	1450
Palladium	7440-05-3	Wire	0.00	0.02	46
Tin	7440-31-5	External plating	1.44	7.55	14375
		TOTALS:	**100.00**	**525.21**	**1,000,000**

525.21 mg Total Mass

Package Homogeneous Materials

300.79	**(mg) Total**	**Mold compound**	**% of Total Weight**	**57.27**
	Solid Epoxy Resin-1	Trade Secret	4.50	
	Solid Epoxy Resin-2	Trade Secret	6.50	
	Hardener	Trade Secret	6.00	
	Carbon Black	1333-86-4	0.50	
	Amorphous Silica	60676-86-0	82.50	
		Total	**100.00**	
209.90	**(mg) Total**	**Leadframe**	**% of Total Weight**	**39.97**
	Copper	7440-50-8	91.29	
	Magnesium	7439-95-4	0.16	
	Nickel	7440-02-0	2.90	
	Silicon	7440-21-3	0.66	
	Silver	7440-22-4	5.00	
		Total	**100.00**	
5.43	**(mg) Total**	**Die**	**% of Total Weight**	**1.03**
	Silicon	7440-21-3	100.00	
		Total	**100.00**	
0.76	**(mg) Total**	**Epoxy**	**% of Total Weight**	**0.14**
	Silver Flake	7440-22-4	75.50	
	Epoxy Acylate	15625-89-5	7.50	
	Substituted Polyamine	68490-66-4	2.00	
	Bisphenol F	28064-14-4	10.00	
	2-Ethylhexyl Glycidyl Ether	2461-15-6	5.00	
		Total	**100.00**	
0.79	**(mg) Total**	**Wire**	**% of Total Weight**	**0.15**
	Copper	7440-50-8	96.90	
	Palladium	7440-05-3	3.10	
		Total	**100.00**	
7.55	**(mg) Total**	**External plating**	**% of Total Weight**	**1.44**
	Tin	7440-31-5	100.00	
525.21		**Total**	**100.00**	100.00

The information contained in this Material Content Declaration (MCD) consists of package-level information and is not part number specific. This information is considered to be sufficiently representative of all part numbers for the package type.

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